

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Roy Knechtel et al.
Serial No. : 10/580,361
Filed : 04/18/2007
International Filing Date : 11/29/2004
Title : PRODUCTION OF SEMICONDUCTOR
SUBSTRATES WITH BURIED LAYERS BY JOINING
(BONDING) SEMICONDUCTOR WAFERS
Attorney Docket : LEO 003 PA
Examiner : Scott B. Geyer
Art Unit : 2812
Confirmation No. : 1718

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

This paper is being filed in response to the Office Action mailed December 4, 2009. Reconsideration is respectfully requested in view of the amendments and remarks below. A request for a three month extension of time is being filed concurrently herewith.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Amendments to the Drawings are set out on page 7 of this paper and include replacement figures for Figs. 1-5.

Remarks/Arguments begin on page 8 of this paper.